

ABSTRACT

The present invention includes: a collet (18) that adsorbs a semiconductor die (15); a suction mechanism (100) that sucks air from a surface (18a) of the collet; a flow rate sensor (106) that detects a suction air flow rate of the suction mechanism; a stage (20) including an adsorption surface (22) for adsorbing a back surface (12b) of a dicing sheet (12); an opening pressure switching mechanism (80) that switches the opening pressure of an opening (23) arranged on the adsorption surface of the stage during pickup between a first pressure close to vacuum and a second pressure close to atmospheric pressure; and a control unit (150). The control unit acquires a time variation of the suction air flow rate detected by the flow rate sensor during pickup of a specific semiconductor die, obtains the easiness of release of the semiconductor die from the dicing sheet according to the time variation, and changes the number of switches during pickup of subsequent semiconductor dies based on the easiness of release. Thereby, it is possible to achieve an appropriate balance between the damage suppression and the pickup speedup of a semiconductor die during pickup.

FIGURE 1